



**Absolute Maximum Ratings** ( $T_A = 25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
<b>Common Ratings</b>			
$V_{DSS}$	Drain-Source Voltage	200	V
$V_{GSS}$	Gate-Source Voltage	$\pm 25$	
$T_J$	Maximum Junction Temperature	150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$ 7 <sup>a</sup>	A
$I_D$	Continuous Drain Current	$T_C=25^\circ\text{C}$ 15 <sup>a</sup>	A
		$T_C=100^\circ\text{C}$ 9 <sup>a</sup>	
$I_{DM}^b$	Pulsed Drain Current	$T_C=25^\circ\text{C}$ 45 <sup>a</sup>	
$P_D$	Maximum Power Dissipation for TO-220	$T_C=25^\circ\text{C}$ 78	W
		$T_C=100^\circ\text{C}$ 31	
$P_D$	Maximum Power Dissipation for TO-220FP	$T_C=25^\circ\text{C}$ 50	W
		$T_C=100^\circ\text{C}$ 20	
$R_{\theta JC}$	Thermal Resistance-Junction to Case for TO-220	1.6	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case for TO-220FP	2.5	$^\circ\text{C/W}$
$I_D$	Continuous Drain Current	$T_A=25^\circ\text{C}$ 2.3	A
		$T_A=70^\circ\text{C}$ 1.8	
$P_D$	Maximum Power Dissipation	$T_A=25^\circ\text{C}$ 2	W
		$T_A=70^\circ\text{C}$ 1.28	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	62.5	$^\circ\text{C/W}$
$I_{AS}^c$	Avalanche Current, Single pulse	$L=0.5\text{mH}$ 2	A
$E_{AS}^c$	Avalanche Energy, Single pulse	$L=0.5\text{mH}$ 1	mJ

Note a : Limited by maximum junction temperature.

Note b : Pulse width limited by safe operating area.

Note c : UIS tested and pulse width limited by maximum junction temperature  $150^\circ\text{C}$  (initial temperature  $T_J=25^\circ\text{C}$ ).

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  Unless Otherwise Noted)

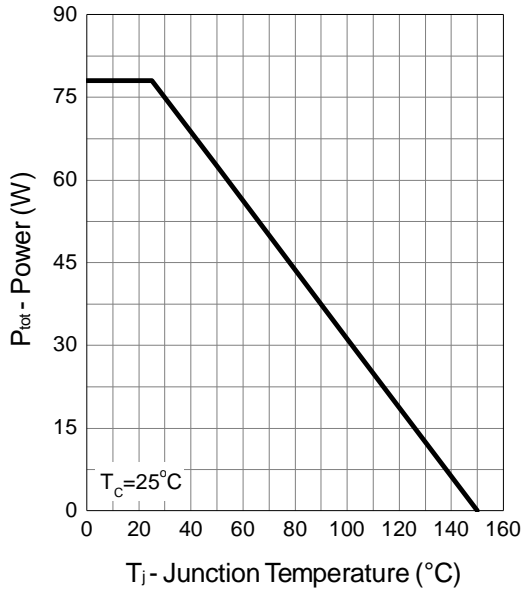
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	200	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=160V, V_{GS}=0V$	-	-	1	$\mu A$
		$T_J=85^\circ C$	-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	2	3	4	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 25V, V_{DS}=0V$	-	-	$\pm 100$	nA
$R_{DS(ON)}^d$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=5A$	-	130	156	m $\Omega$
<b>Diode Characteristics</b>						
$V_{SD}^d$	Diode Forward Voltage	$I_{SD}=3A, V_{GS}=0V$	-	0.8	1.3	V
$t_{rr}$	Reverse Recovery Time	$I_{SD}=5A, dI_{SD}/dt=100A/\mu s$	-	65	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	180	-	nC
<b>Dynamic Characteristics</b> <sup>e</sup>						
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, f=1MHz$	-	2.8	-	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=30V,$ Frequency=1.0MHz	-	1100	1430	pF
$C_{oss}$	Output Capacitance		-	71	-	
$C_{rss}$	Reverse Transfer Capacitance		-	20	-	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=30V, R_L=30\Omega,$ $I_{DS}=1A, V_{GEN}=10V,$ $R_G=6\Omega$	-	10	18	ns
$t_r$	Turn-on Rise Time		-	4.4	8	
$t_{d(OFF)}$	Turn-off Delay Time		-	18	33	
$t_f$	Turn-off Fall Time		-	6.4	12	
<b>Gate Charge Characteristics</b> <sup>e</sup>						
$Q_g$	Total Gate Charge	$V_{DS}=100V, V_{GS}=10V,$ $I_{DS}=5A$	-	19	27	nC
$Q_{gs}$	Gate-Source Charge		-	6.4	-	
$Q_{gd}$	Gate-Drain Charge		-	4.4	-	

Note d : Pulse test ; pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$ .

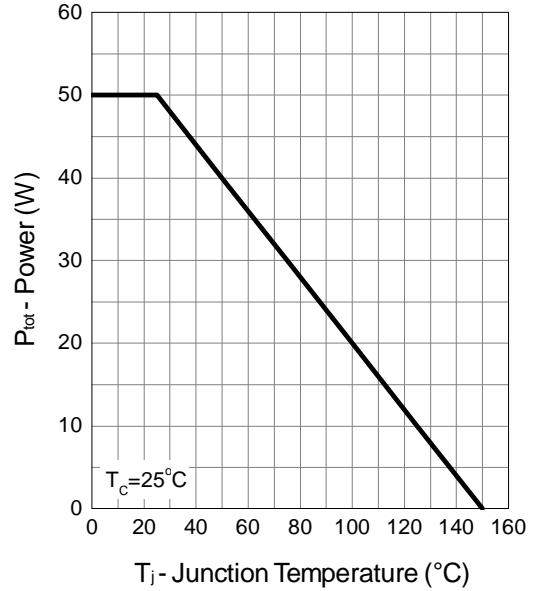
Note e : Guaranteed by design, not subject to production testing.

### Typical Operating Characteristics

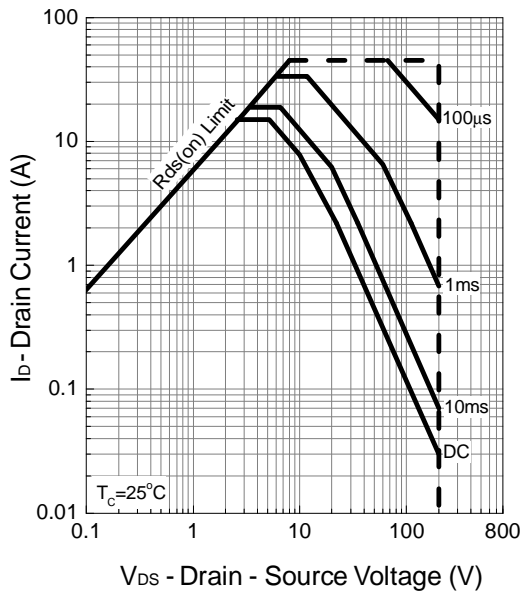
Power Dissipation : TO-220



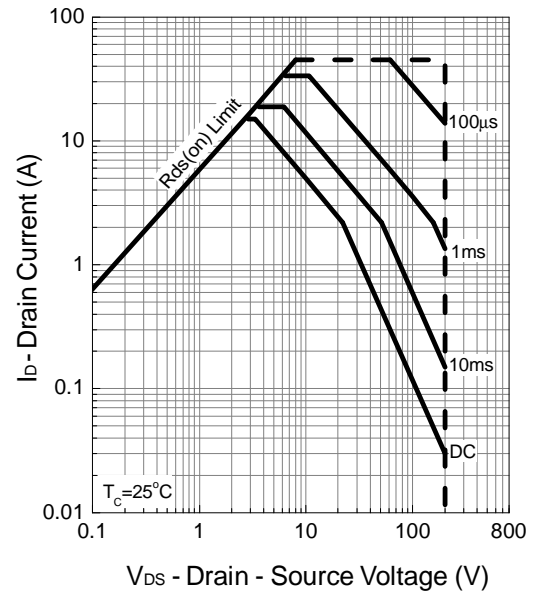
Power Dissipation : TO-220FP



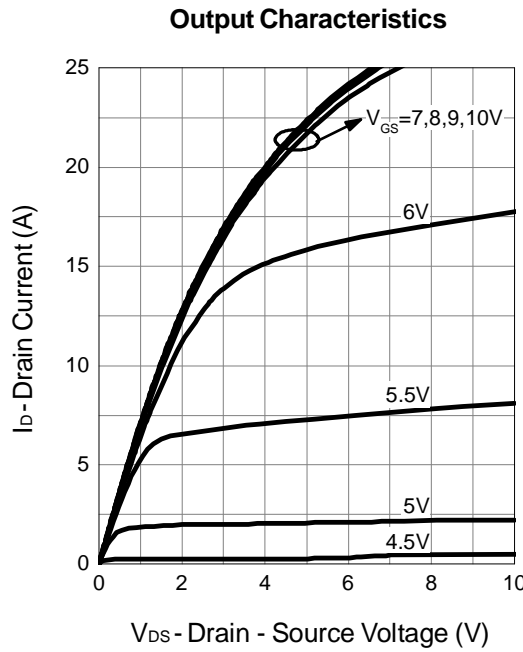
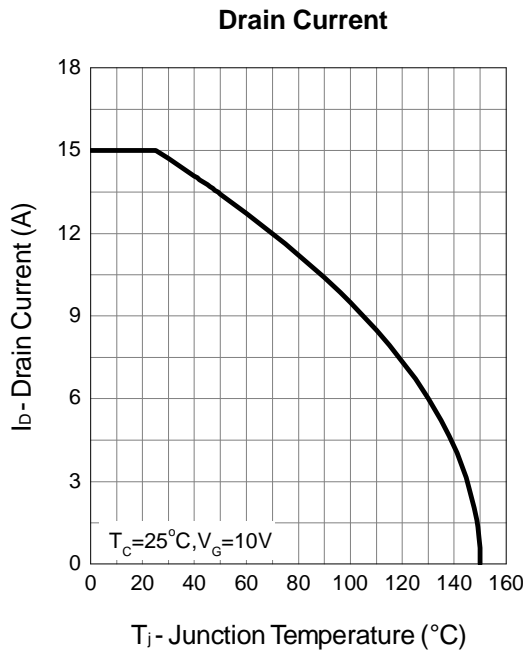
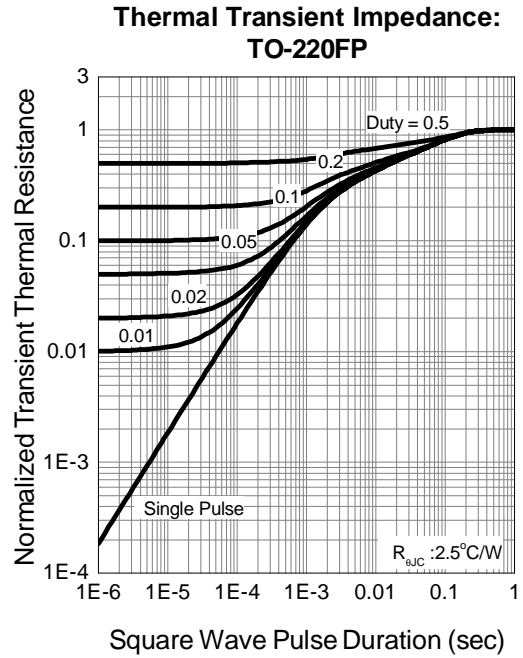
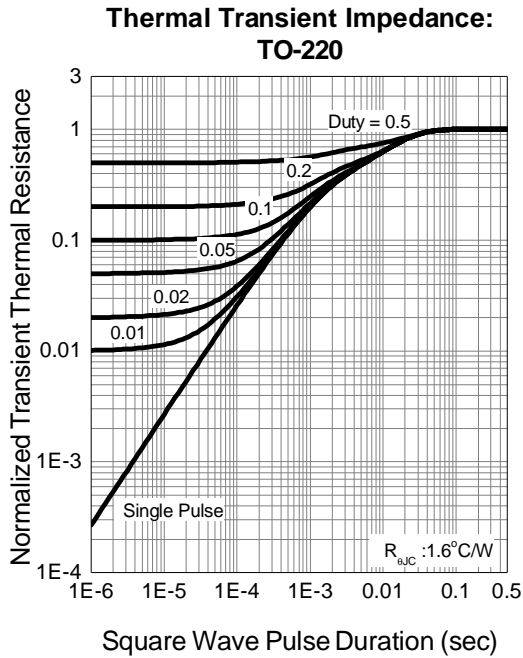
Safe Operation Area : TO-220



Safe Operation Area : TO-220FP

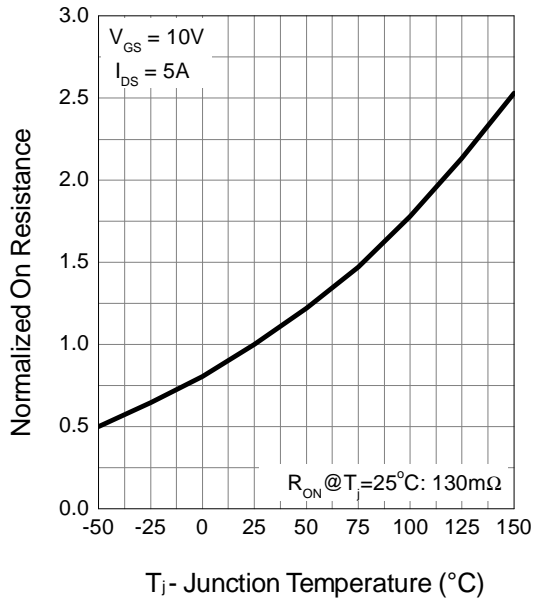


Typical Operating Characteristics (Cont.)

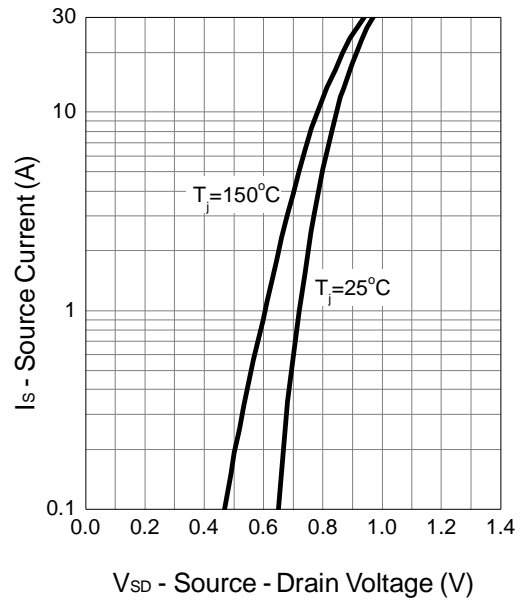


Typical Operating Characteristics (Cont.)

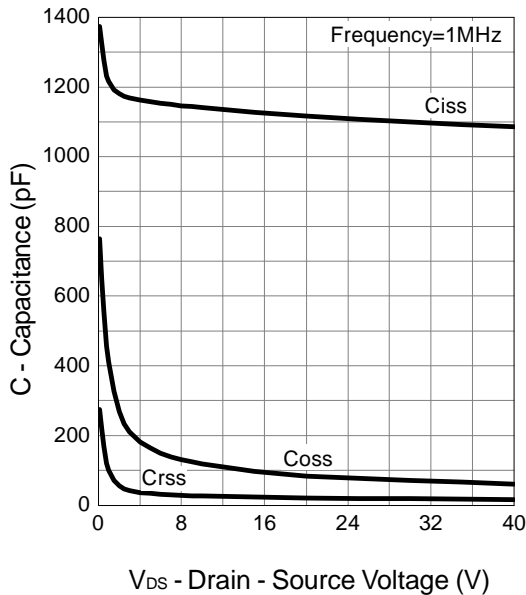
Drain-Source On Resistance



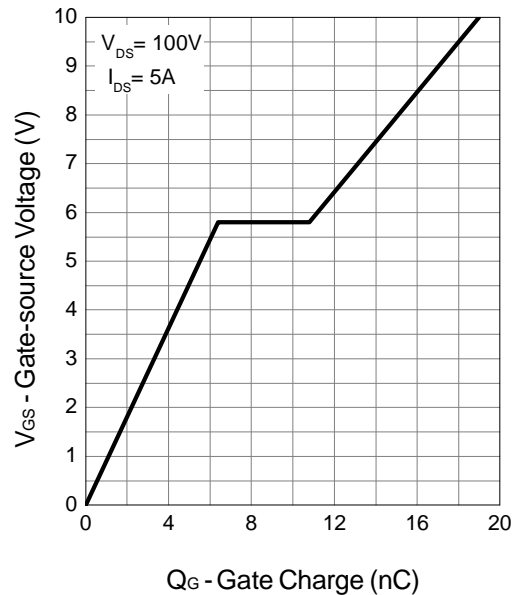
Source-Drain Diode Forward



Capacitance

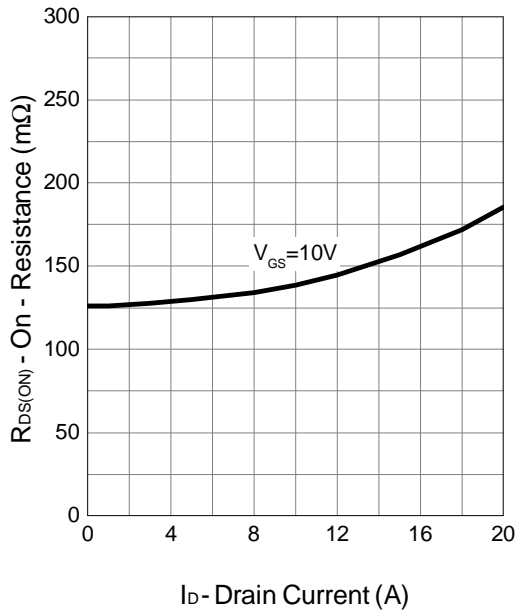


Gate Charge

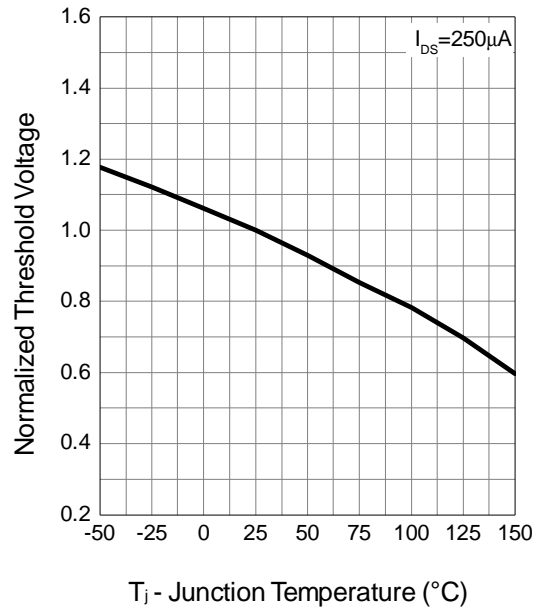


Typical Operating Characteristics (Cont.)

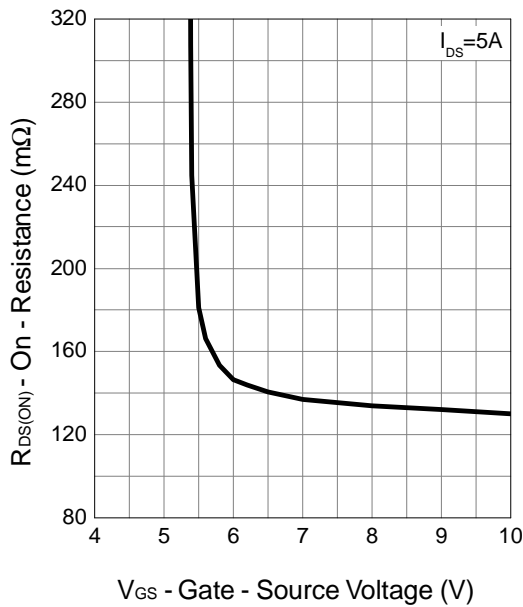
Drain-Source On Resistance



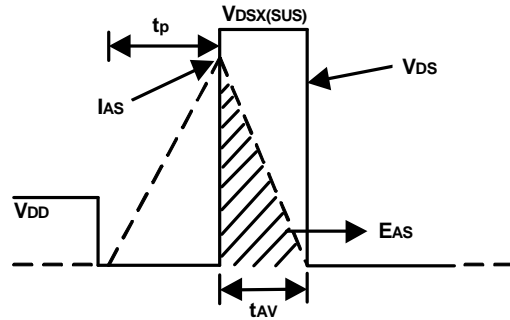
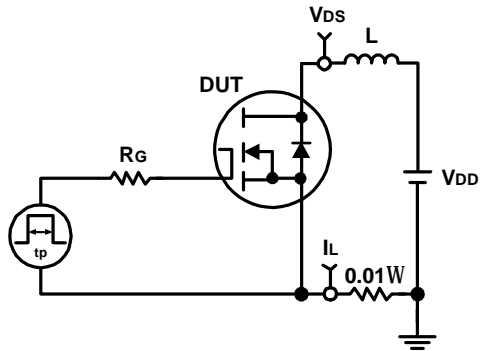
Gate Threshold Voltage



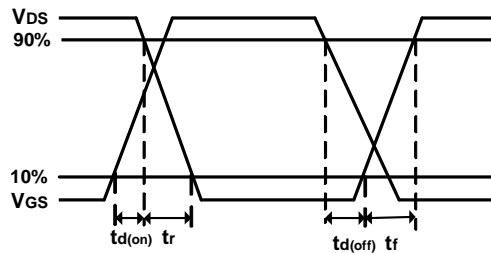
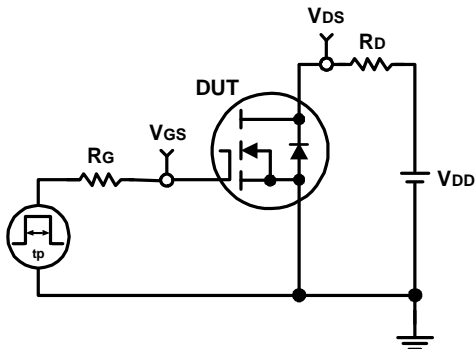
Gate-Source On Resistance



**Avalanche Test Circuit and Waveforms**



**Switching Time Test Circuit and Waveforms**





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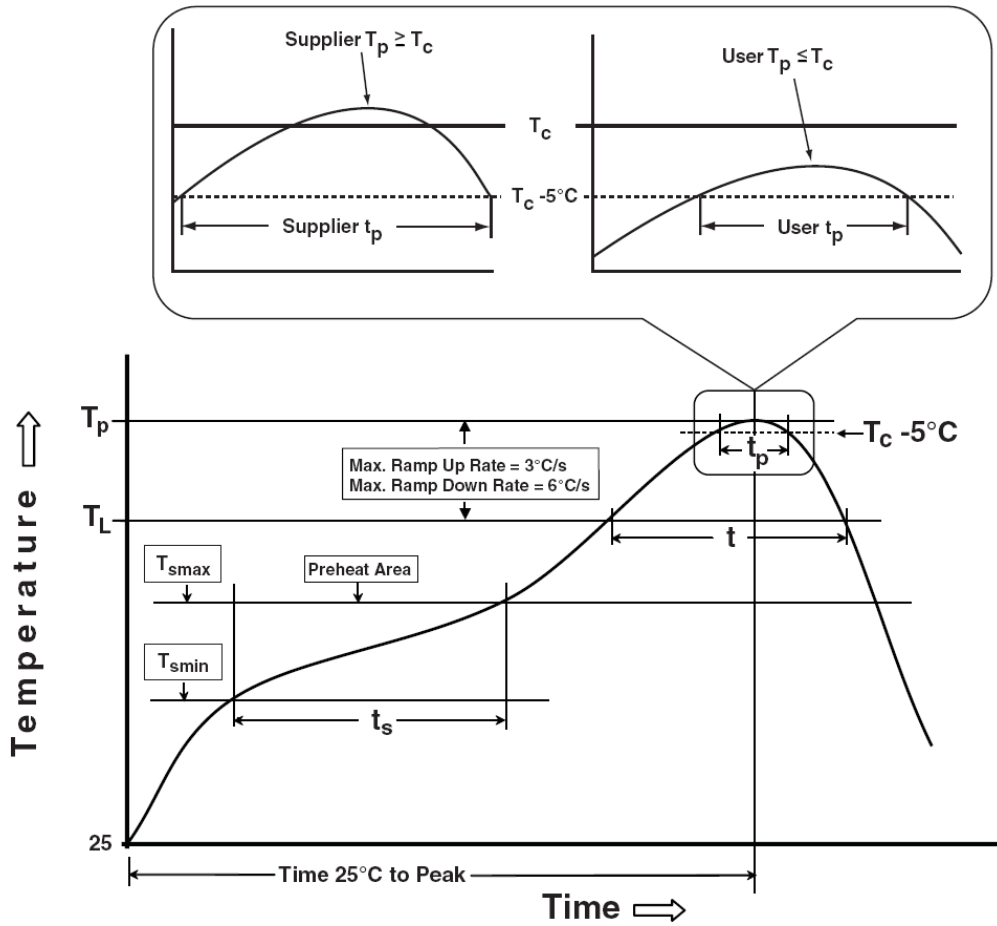
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Classification Profile



## Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat &amp; Soak</b>		
Temperature min ( $T_{smin}$ )	100 °C	150 °C
Temperature max ( $T_{smax}$ )	150 °C	200 °C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max.	3°C/second max.
Liquidous temperature ( $T_L$ )	183 °C	217 °C
Time at liquidous ( $t_L$ )	60-150 seconds	60-150 seconds
Peak package body Temperature ( $T_p$ )*	See Classification Temp in table 1	See Classification Temp in table 2
Time ( $t_p$ )** within 5°C of the specified classification temperature ( $T_c$ )	20** seconds	30** seconds
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum. ** Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.		

Table 1. SnPb Eutectic Process – Classification Temperatures ( $T_c$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures ( $T_c$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

## Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	1000 Hrs, 80% of VDS max @ $T_{jmax}$
HTGB	JESD-22, A108	1000 Hrs, 100% of VGS max @ $T_{jmax}$
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C

## Customer Service

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